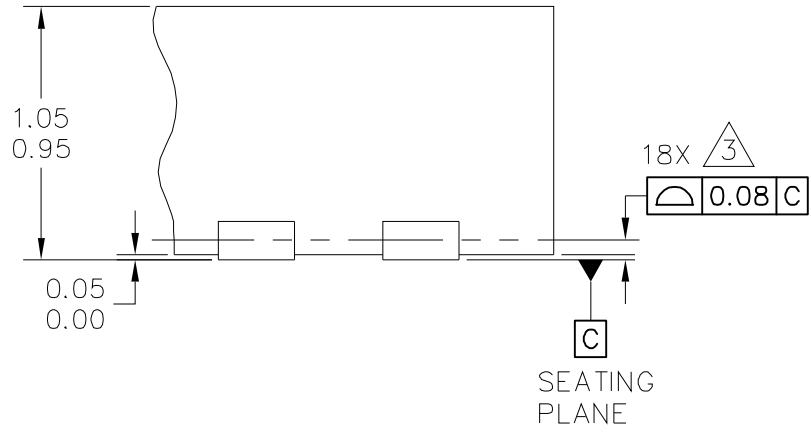


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TITLE: QFN-COL, 3 X 3 X 1, 0.65 PITCH, 12 TERMINAL	DOCUMENT NO: 98ASA00290D	REV: B
	STANDARD: NON-JEDEC	
	SOT1679-1	11 JAN 2016



DETAIL G
VIEW ROTATED 90° CW

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		STANDARD: NON-JEDEC	
		SOT1679-1	11 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

△ 3. COPLANARITY APPLIES TO LEADS.

4. MIN. METAL GAP SHOULD BE 0.2 MM.

△ 5. LEADS 13 TO 18 ARE NOT SOLDERABLE.

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